

STS7NF60L

N-CHANNEL 60V - 0.017 Ω - 7.5A SO-8 STripFETTM II POWER MOSFET

TYPE	V _{DSS}	R _{DS(on)}	ID
STS7NF60L	60 V	< 0.0195 Ω	7.5 A

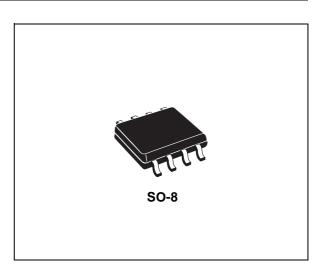
- TYPICAL $R_{DS}(on) = 0.017 \Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- LOW THRESHOLD DRIVE

DESCRIPTION

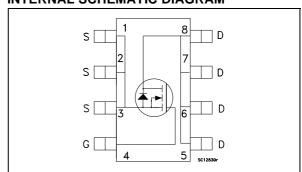
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

APPLICATIONS

- DC MOTOR DRIVE
- DC-DC CONVERTERS
- BATTERY MANAGEMENT IN NOMADIC EQUIPMENT
- POWER MANAGEMENT IN PORTABLE/DESKTOP PCs



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	60	V
V _{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	60	V
V _{GS}	GS Gate- source Voltage ± 16		V
I _D	Drain Current (continuous) at T _C = 25°C	7.5	Α
I _D	Drain Current (continuous) at T _C = 100°C	4.7	Α
I _{DM} (•)	Drain Current (pulsed)	30	Α
P _{tot}	Total Dissipation at T _C = 25°C	2.5	W
E _{AS} (1)	Single Pulse Avalanche Energy	350	mJ

^(•) Pulse width limited by safe operating area.

(1) Starting $T_j = 25 \text{ }^{\circ}\text{C}$, $I_D = 7.5 \text{ A } V_{DD} = 30 \text{ V}$

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THERMAL DATA

•	Rthj-amb(#) T _i	Thermal Resistance Junction-ambient Max Maximum Operating Junction Temperature	50 150	°C/W
	T_{stg}	Storage Temperature	-55 to 150	°C

^(#) When Mounted on 1 inch² FR-4 board, 2 oz of Cu and $t \le 10$ sec.

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	60			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating T_{C} = 125°C			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 16 V			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	1			V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V V _{GS} = 5 V	I _D = 3.5 A I _D = 3.5 A		0.017 0.019	0.0195 0.0215	Ω Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs}	Forward Transconductance	$V_{DS} = 15 \text{ V}$ $I_{D} = 3.5 \text{ A}$		13		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$, $f = 1 MHz$, $V_{GS} = 0$		1700 300 100		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time	$\begin{array}{ccc} V_{DD} = 30 \text{ V} & I_D = 3.5 \text{ A} \\ R_G = 4.7 \Omega & V_{GS} = 4.5 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{array}$		15 27		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V_{DD} = 48V I_D 7.5A V_{GS} =4.5V (see test circuit, Figure 2)		25 4.5 7	34	nC nC nC

SWITCHING OFF (*)

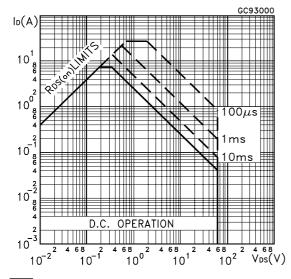
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time	$V_{DD} = 30 \text{ V}$ $R_G = 4.7\Omega$, (Resistive Load, Fig	$I_D = 3.5 \text{ A}$ $I_{GS} = 4.5 \text{ V}$ ure 1)		47 20		ns ns

SOURCE DRAIN DIODE (*)

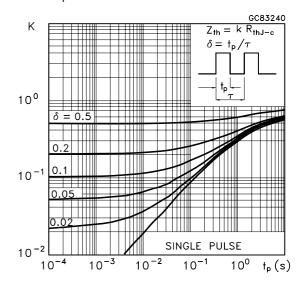
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (•)	Source-drain Current Source-drain Current (pulsed)				7.5 30	A A
V _{SD}	Forward On Voltage	$I_{SD} = 7.5 \text{ A}$ $V_{GS} = 0$			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	I_{SD} =7.5 A di/dt = 100A/µs V_{DD} = 20 V T_j = 150°C (see test circuit, Figure 3)		55 110 3.9		ns nC A

^(*) Pulse width \leq 300 µs, duty cycle 1.5 %.

Safe Operating Area



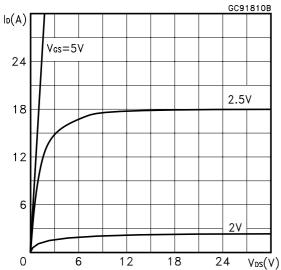
Thermal Impedance



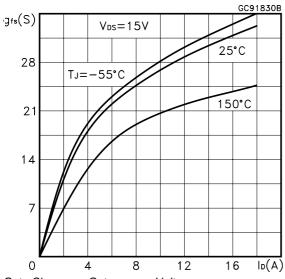
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^(•)Pulse width limited by safe operating area.

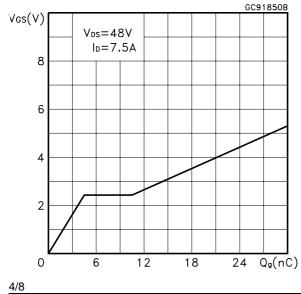
Output Characteristics



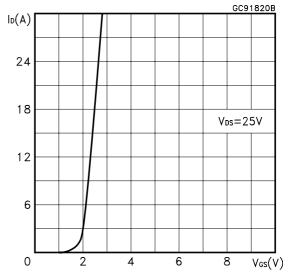
Transconductance



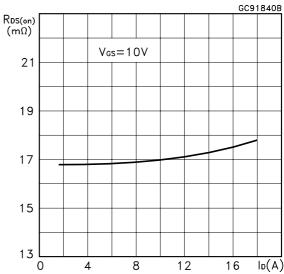
Gate Charge vs Gate-source Voltage



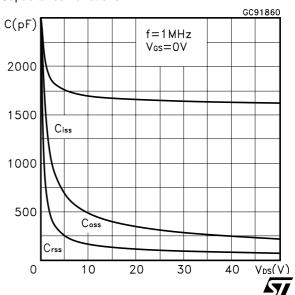
Transfer Characteristics



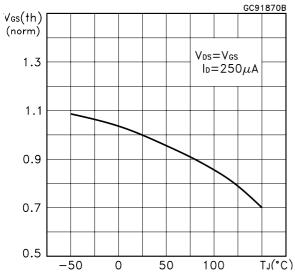
Static Drain-source On Resistance



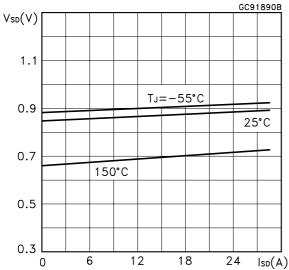
Capacitance Variations



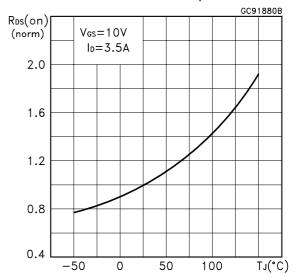
Normalized Gate Threshold Voltage vs Temperature



Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature

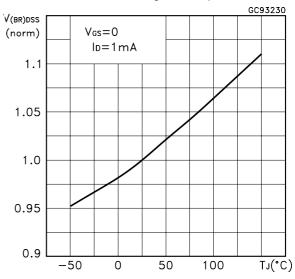


Fig. 1: Unclamped Inductive Load Test Circuit

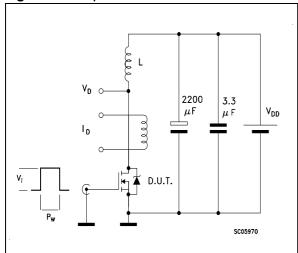


Fig. 3: Switching Times Test Circuits For Resistive Load

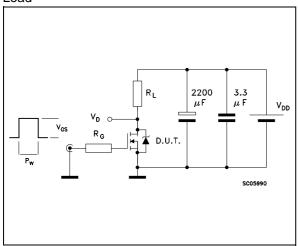


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

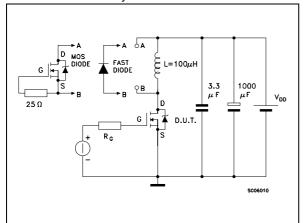


Fig. 2: Unclamped Inductive Waveform

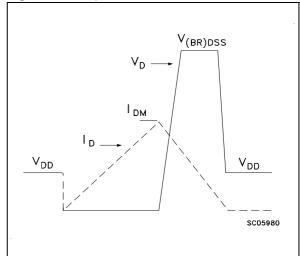
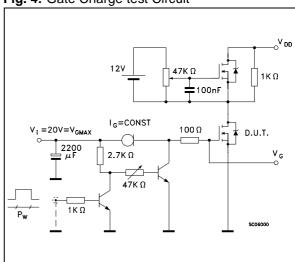
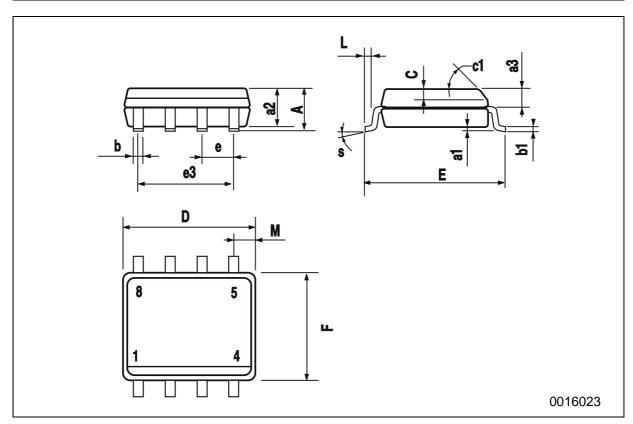


Fig. 4: Gate Charge test Circuit



SO-8 MECHANICAL DATA

DIM.		mm		inch			
DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			1.75			0.068	
a1	0.1		0.25	0.003		0.009	
a2			1.65			0.064	
a3	0.65		0.85	0.025		0.033	
b	0.35		0.48	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С	0.25		0.5	0.010		0.019	
c1			45	(typ.)			
D	4.8		5.0	0.188		0.196	
Е	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		3.81			0.150		
F	3.8		4.0	0.14		0.157	
L	0.4		1.27	0.015		0.050	
М			0.6			0.023	
S			8 (r	nax.)			



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